

PRODUCT/PROCESS CHANGE NOTIFICATION

PCN APM-IPC/10/5740 Notification Date 07/06/2010

Alternative die for TL431C

Table 1. Change Implementation Schedule

Forecasted implementation date for change	30-Sep-2010
Forecasted availability date of samples for customer	29-Jun-2010
Forecasted date for STMicroelectronics change Qualification Plan results availability	29-Jun-2010
Estimated date of changed product first shipment	05-Oct-2010

Table 2. Change Identification

Product Identification (Product Family/Commercial Product)	see attached list
Type of change	Waferfab process change
Reason for change	Capacity optimization
Description of the change	Following Divisional commitments towards a continuous improvement philosophy an alternative die in same technology and same wafer Fab has been qualified for Voltage reference TL431C. It allows ST to have more flexibility and improve service and delivery versus customers
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Traceability codes
Manufacturing Location(s)	

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Table 3. L	ist of A	Attachments
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Customer Part numbers list	
Qualification Plan results	

Customer Acknowledgement of Receipt	PCN APM-IPC/10/5740
Please sign and return to STMicroelectronics	Sales Office Notification Date 07/06/2010
□ Qualification Plan Denied	Name:
□ Qualification Plan Approved	Title:
	Company:
□ Change Denied	Date:
□ Change Approved	Signature:
Remark	

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DOCUMENT APPROVAL

Name	Function	
Riviera, Antonio	Division Marketing Manager	
Naso, Lorenzo	Division Product Manager	
Motta, Antonino	Division Q.A. Manager	

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Presentation & main results of qualification

The **1431** is a programmable voltage reference in SO8 batwing package with an output voltage from 2.5 to 36V. The sink current capability from 1 to 100mA. The voltage precision are 2.500V +/-0.4% and +/-0.25%.

The qualification has been combined with the **0431** (same product characteristics with the voltage precision of 2.5V +/-1% and +/-2%.), belonging to the same family (as defined in the AEC Q100 appendix 1).

Electrical results:

Product (lot)	Package/plant	
1431	SO8 / BOUSKOURA	

The yield analysis conforms to ST standard results

Electrical parameters distribution on 50 pieces at TAMB = 25℃ and at cold and hot temperatures

The results conform to datasheet specifications.

ESD measurement:

The results conform to datasheet specifications (see ESD certificate).

The units have been tested at 25℃ and hot test before and after electrostatic discharge.

Latch-up measurement was performed according to ST specification (n 0018695):

No latch-up was observed.

The units have been tested at 25℃ and hot test before and after stress.

Design FMEA: see appendix

Not available for the products designed before 2002 or designed from an existing old product.

Environmental and Quality information:

ST is certified ISO/TS16949:

certificate: 9136.STM2; approval authority IATF/CISQ-Auto.

ST Quality international awards:

EMAS & ISO 14001 OHSAS 18001 Environmental Management System; for all sites

Quality and Reliability tests were performed according to the qualification plan

Reliability test High Temperature Bias test (HTB)	Nb of rejects	Package/plant	Test circuit
T°AMB = 150℃ - Duration = 1000h			
78u 1431 standard diff. lot Bouskoura Plant	0/78	SO8/Bouskoura	N420AAD
	5.1.5		
The units have been tested at 25℃; -40℃ and 125℃ be-			
fore and after HTB			
Temperature & Humidity bias (THB) Including precondi-			
tioning according to MSL 1 (J-STD-020 for SMD package).			
T°AMB = 85°C humidity = 85°% Duration = 1000h			
78u 1431 standard diff. lot Bouskoura Plant	0/78	SO8/Bouskoura	N420AAD
The units have been tested at 25℃ and 125℃ before and	0,10	000,2000.100.10	
after THB			
Temperature cycling (TC) (THB) Including preconditioning			
according to MSL 1 (J-STD-020 for SMD package).			
T°AMB = -65/150℃ Nb cycles = 1000			
78u 1431 standard diff. Iot Bouskoura Plant	0/78	SO8/Bouskoura	Not applicable
The units have been tested at 25℃ and 125℃ before and	0/10	CCG/ Bodonoura	
after TC & bond pull test on 5 units after TC			
Pressure pot test (PPT) (THB) Including preconditioning			
according to MSL 1 (J-STD-020 for SMD package).			
T°AMB = 121℃ Pressure = 2atm - Duration = 240h			
78u 1431 standard diff. lot Bouskoura Plant	0/78	SO8/Bouskoura	Not applicable
The units have been tested at 25°C before and after PPT	0/10	OCO/ Bodonodia	
Gate leakage (GL)			
6u 1431 standard diff, lot Bouskoura Plant	0/6	SO8/Bouskoura	Not applicable
The units have been tested at 25℃ before and after GL			
Early Life failure rate (ELFR)			
T°AMB = 125℃ - Duration = 48h			
400u 1431 standard diff. lot Bouskoura Plant	0/400	SO8/Bouskoura	N420AAD
Solderability (SD)			
1 lot	Not available	SO8/Bouskoura	Not applicable
Physical dimension (PD)	-		11
1 lot	Not available	SO8/Bouskoura	Not applicable
Bond Pull Strength (BPS)			
1 lot	Not available	SO8/Bouskoura	Not applicable
Bond Shear Strength (BS)			
1 lot	Not available	SO8/Bouskoura	Not applicable

Conclusion

Electrical and reliability results meet or exceed the requirements set in the ST qualification program. The results conform to datasheet specifications and Product Qualification Plan PQP reference **ADCS_8137636** .

This device is qualified for the SO8 package, grade 1 according to the AEC-Q100.

Detailed results are available upon request

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